



尼得科超眾科技股份有限公司
Nidec Chaun-Choung Technology Corp.

Date: Aug. 31st, 2021

Nidec Chaun-Choung Technology Corporation

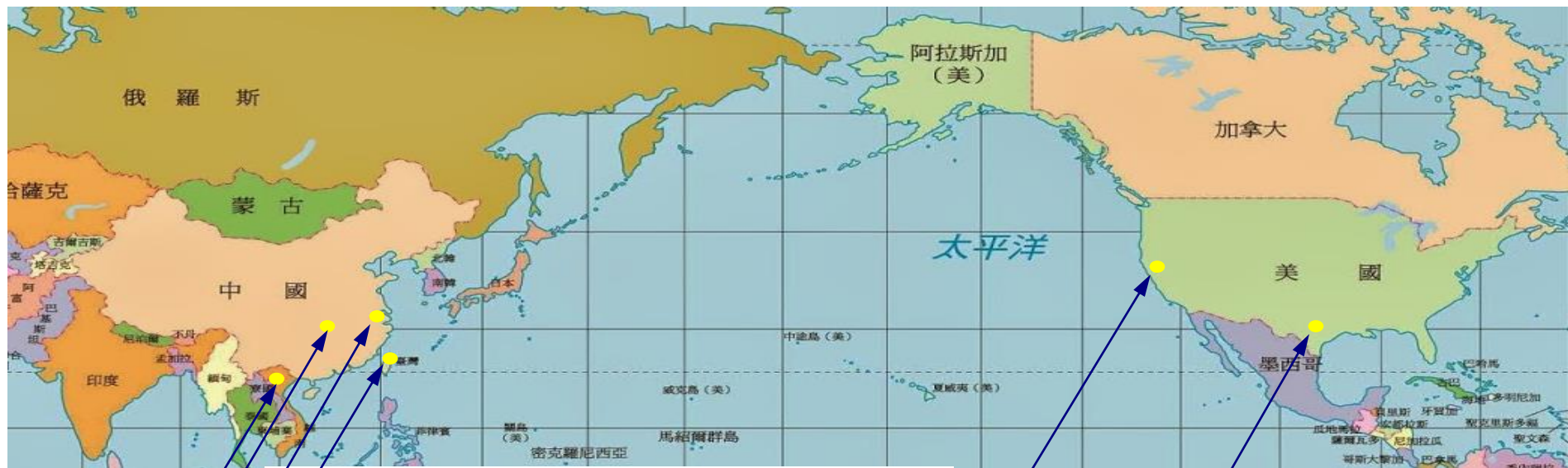
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Company Profile

- **New Company Name:** Nidec Chaun-Choung Technology Corp. (Since Jan. 2021)
- **Founded :** Dec.14. 1973
- **Nidec:** Hold 85.86% shares, as a major shareholder (Jul. 9th, 2021).
- **Address :** No. 184-3, Zhongxing N. St., Sanchong Dist., New Taipei City 241, Taiwan
- **Capital :** NT\$ 863,434 (K)
- **Main Business :** Heat Sink & Thermal Solutions
- **WW Factories & Offices**

WW Factories & Offices



Nidec Chaun-Chong Technology: (NCCI)

New Taipei City, Taiwan

Nidec Jue-Chong Electronics: (NJCI)

Kunshan Jiangsu, China

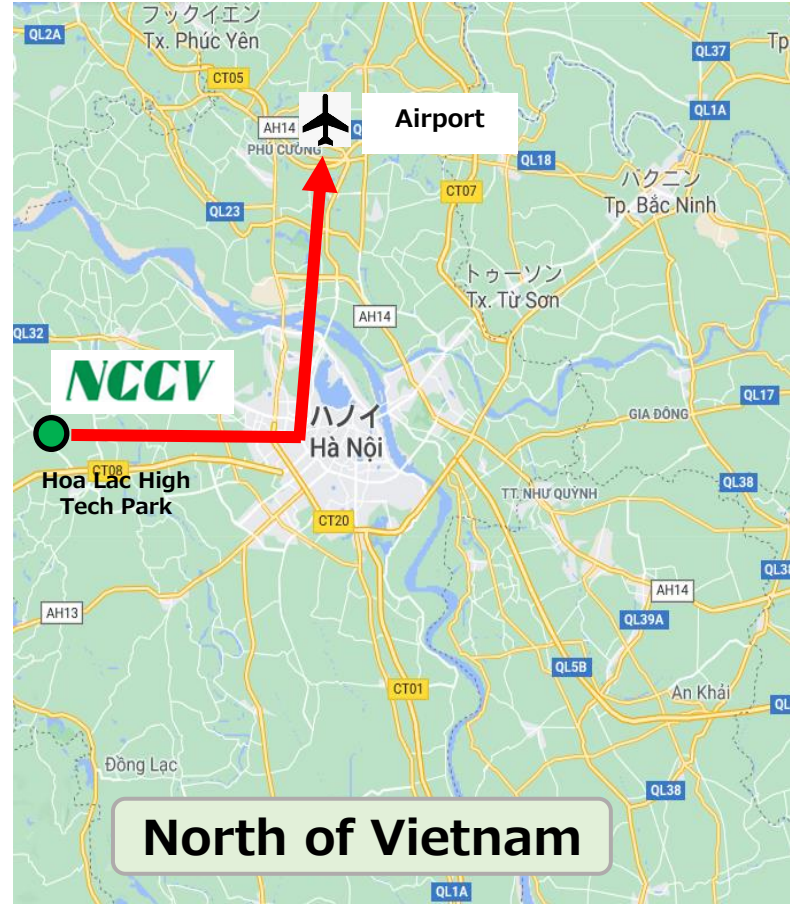
Nidec Cyunsiang High Tech: (NCSI) – Chongqing, China

Nidec Chaun-Chong Vietnam Corp.: (NCCV) – Hanoi, Vietnam

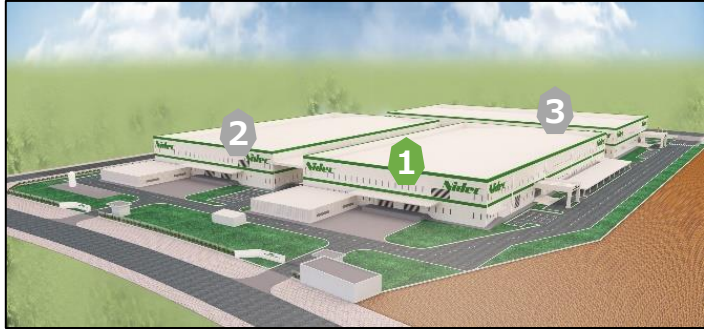
NCCI AMERICA INC- Austin, USA

NCCI AMERICA INC- CA, USA

New Manufacture Base: NCCV



New Manufacture Base: NCCV



Address

Lot CN1-05-1, 5&6,
Hi-tech Industrial, Zone 1,
Hoa Lac Hi-tech Park, Thach That
Dist., Hanoi, Vietnam

Site area

Total: 60,690m² in 3 phases

- 1st Phase: 20,460m² (Done)
- 2nd Phase: 20,460m² (2022~)
- 3rd Phase: 19,770m² (2023~)

Products

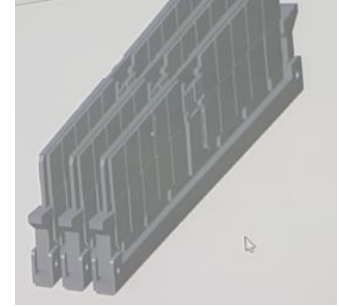
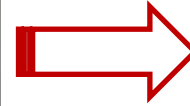
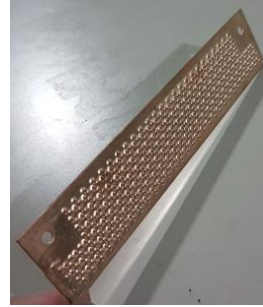
- Thermal Module
- Heat Pipe
- Vapor Chamber

Registered capital

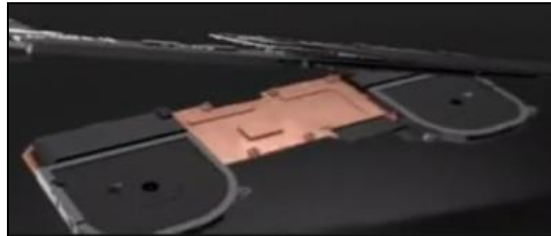
USD 34,904,000

Focus Developing Products - I

- **Slim Thermal Solution for DRAM**
Ultra Thin VC ($t < 1.0\text{mm}$) for 6 Watts

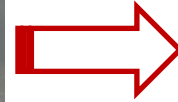


- **Slim Thermal Solution for Gaming NB**
Slim VC ($1.0\text{mm} \leq t \leq 2.0\text{mm}$) for CPU+GPU 140 Watts



Focus Developing Products - II

- **Hi-Power VC Thermal Solution for HPC Server**
High Heat Flux Vapor Chamber > 80 W/cm²



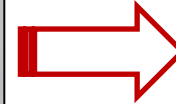
- **Hi-power Heat Pipe Module for 5G Telecom Switch**
Long Heat Pipe L ≥ 600 mm for 500Watts



Focus Developing Products - III

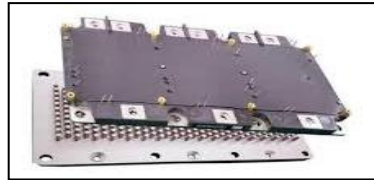
- **Ultra-thin Thermal Solution for 5G Smart Phone**

- VC Thickness 0.25mm – 0.35mm



- **Rugged Thermal Solution for Automation**

- VC + Liquid Cooling ~ 45KW



- **Liquid Cooling Solution for Rack / Tower Server**

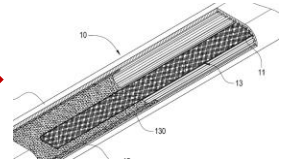
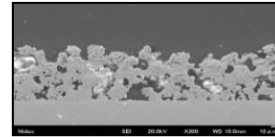
- CDU $\leq 5U$



Competitive Advantages

- **Metallurgy & Wick Technology –**

Nidec & NCCI team with strong basic research and Proprietary multi-wick design to support Ultra-thin / Hi-power Thermal Solutions.



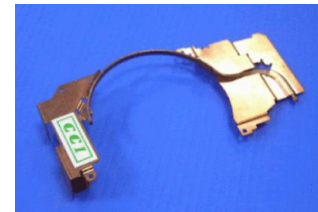
- **Automation Equipment Building in House –**

Nidec & NCCI team up to develop manufacturing machine from sample to mass production, and know-how in house.

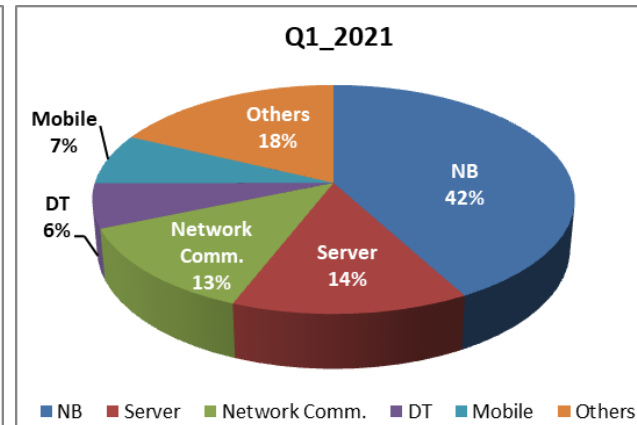
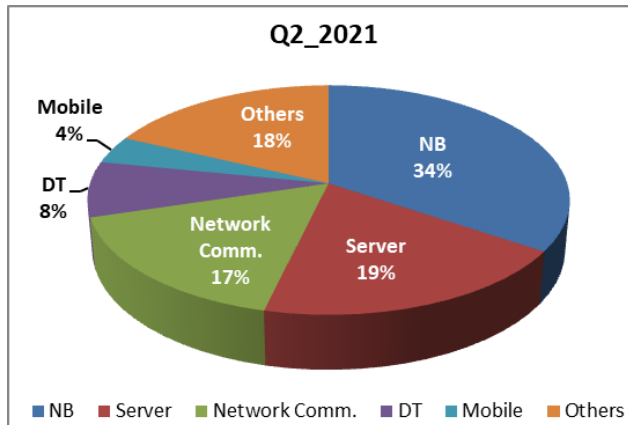
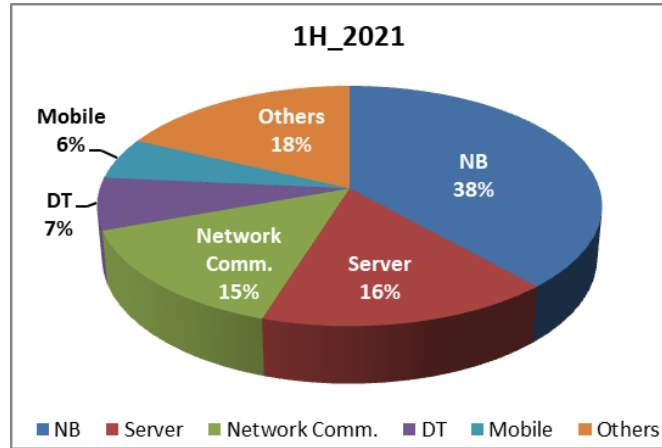


- **Active & Passive Horizontal Division of Collaborating –**

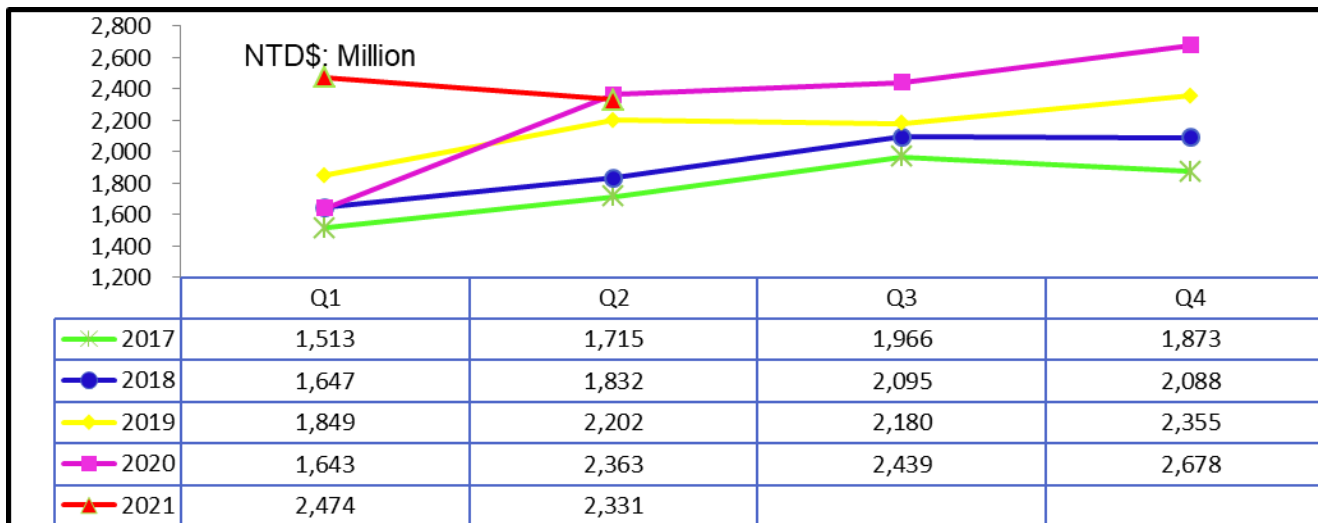
Nidec is good at Fan/Pump active solution and NCCI is good at HP/VC passive solution, collaboration to provide customer total solution with best options.



Product Lines



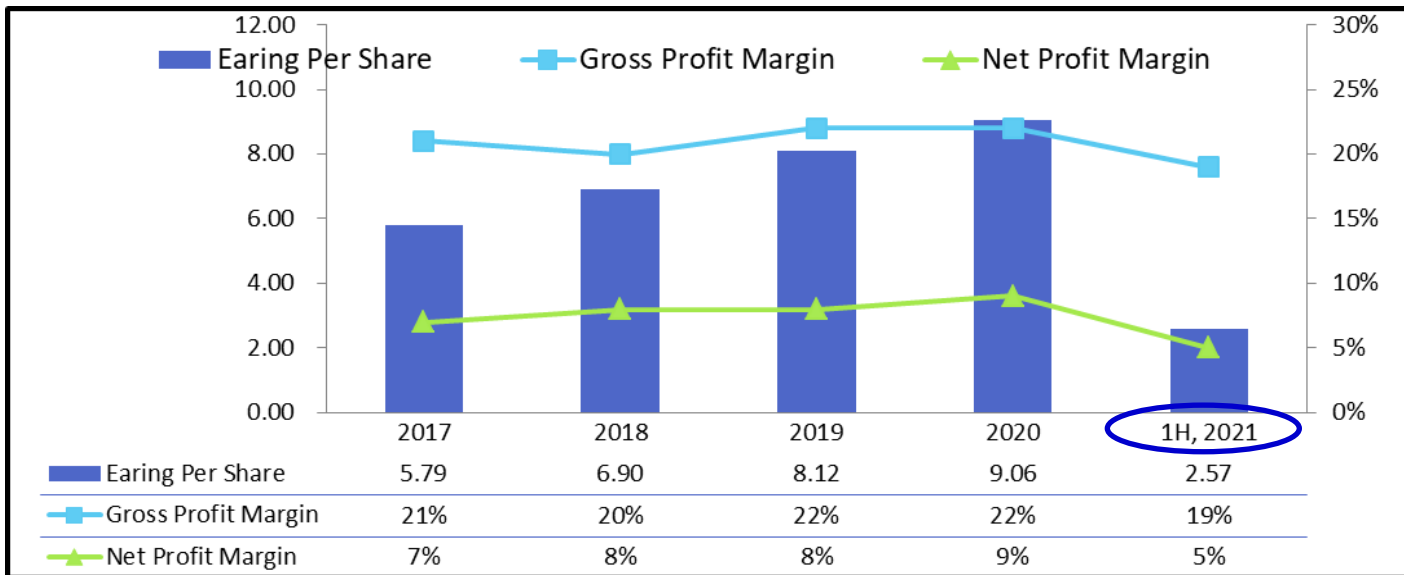
Revenue



	Q1	Q2	Q3	Q4	Total
2021	2,474	2,331			4,805
2020	1,643	2,363	2,439	2,678	9,123
2019	1,849	2,202	2,180	2,355	8,586
2018	1,647	1,832	2,095	2,088	7,662
2017	1,513	1,715	1,966	1,873	7,067

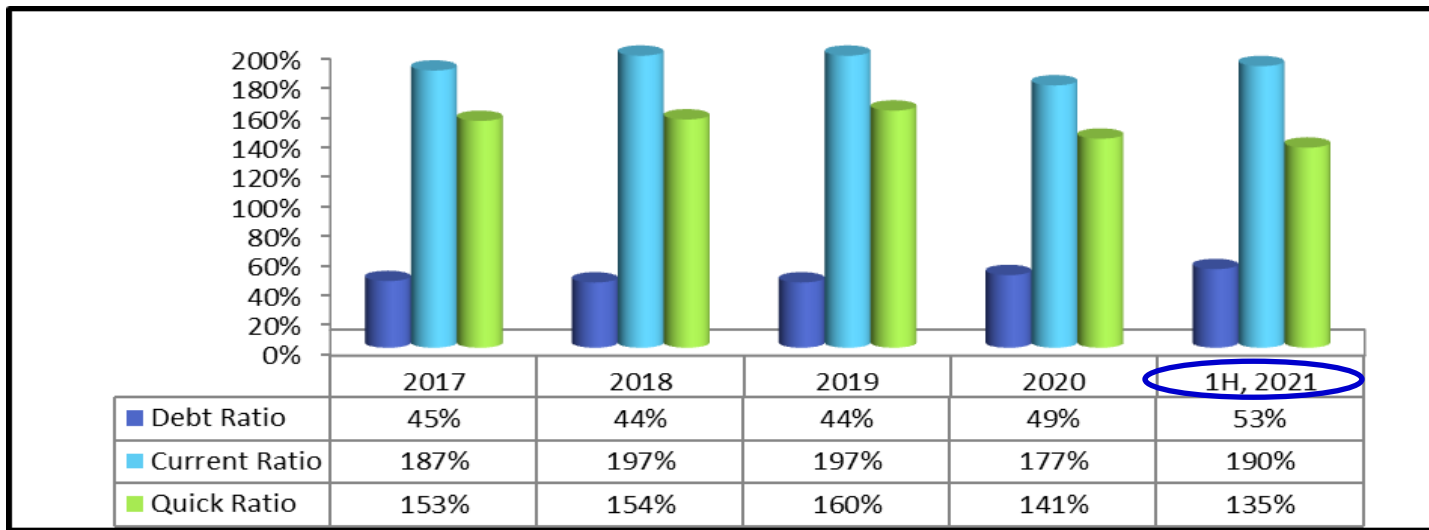
NTD\$: Million

Financial Index I.



Years Items	2017	2018	2019	2020	1H, 2021
Earing Per Share	5.79	6.90	8.12	9.06	2.57
Gross Profit Margin	21%	20%	22%	22%	19%
Net Profit Margin	7%	8%	8%	9%	5%

Financial Index II



Years Items	2017	2018	2019	2020	1H, 2021
Debt Ratio	45%	44%	44%	49%	53%
Current Ratio	187%	197%	197%	177%	190%
Quick Ratio	153%	154%	160%	141%	135%

Nidec

All for dreams